



S/N 10/052089

PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Krishna Seshan et al.	Examiner:	Kiley Shawn Stoner
Serial No.:	10/052089	Group Art Unit:	1725
Filed:	January 16, 2002	Docket No.:	884.659US1
Title:	A WIRE-BONDABLE PROCESS FLOW COMPATIBLE WITH CU-M6		
Assignee:	Intel Corporation	Customer No.:	21186

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AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicant has reviewed the Office Action mailed on May 29, 2003. Please amend the above-identified patent application as follows.

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**GROUP 1700**